

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Joseph E. Geusic et al.

Title: INTEGRATED CIRCUITS USING OPTICAL FIBER INTERCONNECTS FORMED  
THROUGH A SEMICONDUCTOR WAFER

Docket No.: 303.390US4

Serial No.: 10/772,606

Filed: February 5, 2004

Due Date: October 28, 2005

Examiner: Julio J Maldonado

Group Art Unit: 2823

Customer No.: 21186

Confirmation No.: 5065

Commissioner for Patents

**Notice of Allowance Date:**

Attn: MAIL STOP ISSUE FEE

July 28, 2005

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the attached:

☒ A check in the amount \$1400.00 to cover the Large Entity Issue Fee Payment.

☒ A check in the amount \$9.00 to cover the Extra Patent Copies Fee (3 copies).

☒ Issue Fee Transmittal (Form PTOL-85).

☒ Communication Re: Fee Address (1 page).

☒ Supplemental Amendment Under 37 C.F.R § 1.312 (3 pages).

☒ A check in the amount \$300.00 to cover the Publication Fee Payment.


☒ A return postcard.

**Please charge any additional required fees for the Issue Fee Payment or credit overpayment to Deposit Account No. 19-0743.**

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

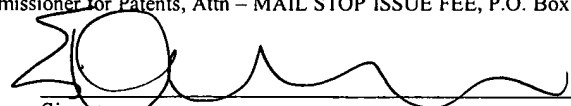
Customer Number: 21186

By

  
Viet V. Tong  
Reg. No. 45,416  
VVT:CMG:eho

**CERTIFICATE UNDER 37 CFR 1.8:** The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, Attn – MAIL STOP ISSUE FEE, P.O. Box 1450, Alexandria, VA 22313-1450, on this 28 day of October, 2005.

Eric H. Olson  
Name

  
Signature